



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20200929003.1**  
**Add Cu as Alternative Wire Base Metal for Selected Device(s)**  
**Change Notification / Sample Request**

**Date:** October 01, 2020  
**To:** SFO TECHNOLOGIES PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**20200929003.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
LM22676TJ-ADJ/NOPB	null
LM22679TJE-5.0/NOPB	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20200929003.1		<b>PCN Date:</b>	Oct. 1, 2020							
<b>Title:</b>	Add Cu as Alternative Wire Base Metal for Selected Device(s)										
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Dec 31, 2020		<b>Estimated Sample Availability:</b>	Date provided at sample request							
<b>Change Type:</b>											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process						
<b>PCN Details</b>											
<b>Description of Change:</b>											
Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:											
<table border="1"> <thead> <tr> <th>Material</th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Wire type</td> <td>Au</td> <td>Cu</td> </tr> </tbody> </table>						Material	Current	Proposed	Wire type	Au	Cu
Material	Current	Proposed									
Wire type	Au	Cu									
<b>Reason for Change:</b>											
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock											
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>											
None.											
<b>Anticipated impact on Material Declaration</b>											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.								
<b>Changes to product identification resulting from this PCN:</b>											
None.											
<b>Product Affected:</b>											
LM22670TJ-5.0/NOPB	LM22676TJ-5.0/NOPB	LM22677TJE-ADJ/J7002402	LM22679TJE-5.0/NOPB								
LM22670TJ-ADJ/NOPB	LM22676TJ-ADJ/J7002452	LM22677TJE-ADJ/NOPB	LM22679TJE-ADJ/NOPB								
LM22670TJE-5.0/NOPB	LM22676TJ-ADJ/NOPB	LM22678TJ-5.0/NOPB	LV13603ATJ-ADJ/NOPB								
LM22670TJE-ADJ/NOPB	LM22676TJE-5.0/NOPB	LM22678TJ-ADJ/J7002567	LV13603ATJ-H/NOPB								
LM22673TJ-5.0/NOPB	LM22676TJE-ADJ/J7002453	LM22678TJ-ADJ/NOPB	LV13603BTJ-ADJ/NOPB								
LM22673TJ-ADJ/J7002341	LM22676TJE-ADJ/NOPB	LM22678TJE-5.0/NOPB	LV13603BTJ-H/NOPB								
LM22673TJ-ADJ/NOPB	LM22677TJ-5.0/NOPB	LM22678TJE-ADJ/J7002566	LV13603CTJ-ADJ/NOPB								

LM22673TJE-5.0/NOPB	LM22677TJ-ADJ/J7002401	LM22678TJE-ADJ/NOPB	LV13603CTJ-H/NOPB
LM22673TJE-ADJ/J7002342	LM22677TJ-ADJ/NOPB	LM22679TJ-5.0/NOPB	LV13605TJ-ADJ/NOPB
LM22673TJE-ADJ/NOPB	LM22677TJE-5.0/NOPB	LM22679TJ-ADJ/NOPB	LV13605TJ-H/NOPB

## Qualification Report

Approved on 18-Sep-2020

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>LM22670TJ5M64Y</u>	QBS Package Reference: <u>TPS92613QNDRRQ1</u>
AC	Autoclave 121C	96 hours	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96	QBS	3/231/0
HTSL	High Temp Storage Bake 150C	1000hrs	QBS	1/45/0
TC	Temperature Cycle, -65/150C	500 cycles	3/231/0	-

- QBS: Qual By Similarity

- Qual Device LM22670TJ5M64Y is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>

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